Atty. Dkt. No. APPM/1931.P1/CPI/COPPER/PJS



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

§

In re Application of:

Xi et al.

Patent No.: 7,026,238

Issued:

April 11, 2006

Serial No.: 10/052,681

Filed:

January 17, 2002

For:

RELIABILITY BARRIER

INTEGRATION FOR CU

APPLICATION

Certificate of Correction Branch Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

Group Art Unit: 2814

Examiner:

Ginette Peralta

Certificate

JUL 0.6 2006

of Correction

CERTIFICATE OF MAILING

37 CFR 1.8

6/26/06

Signature

REQUEST FOR CERTIFICATE OF CORRECTION

Attached is a Certificate of Correction for correcting several errors throughout the printed patent.

A copy of the Combined Declaration and Power of Attorney indicating the correct city of residence for inventor Paul Frederick Smith is attached. The omitted references were initialed by the Examiner in the Notice of Allowability dated December 31, 2003, signed December 10, 2003, and in the Office Action dated June 19, 2003, signed June 11, 2003. Copies of the PTO-892s and PTO-1449s showing the omitted references initialed by the Examiner are attached.

Applicants submit that at least one of the other typing errors mentioned above was made by the applicants. Therefore, please charge the fee of \$100.00 to deposit account no. 20-0782/APPM/1931.P1 (KMT).

07/03/2006 HDEMESS2 00000077 200782

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Respectfully submitted,

Keith M. Tackett

Registration No. 32,008

Page 1

PATTERSON & SHERIDAN, L.L.P. 3040 Post Oak Blvd. Suite 1500 Houston, TX 77056 Telephone: (713) 623-4844

Facsimile: (713) 623-4846 Agent for Applicant(s)

Page 2

CERTIFICATE OF CORRECTION

PATENT NO.: 7,026,238

Page <u>1</u> of <u>3</u>

APPLICATION NO.: 10/052,681

DATED: Apr. 11, 2006

INVENTOR(S): Ming XI, Paul Frederick SMITH, Ling CHEN, Michael X. YANG, Mei CHANG, Fusen CHEN, Cristophe

MARCADAL, Jenny C. LIN

It is certified that error appears in the above-identified patent and that said Letters Patent are hereby corrected as shown below:

On the Cover of the Patent

Item [75], Inventors: Change Paul Frederick Smith's city of residence from "San Jose, CA" to -- Campbell, CA--

Item [56], References Cited, U.S. PATENT DOCUMENTS: Please add the following references:

0 007 077	0/0000	D 1:1: 1:1	400/007
6,607,977	8/2003	Rozbicki et al	
6,498,091	12/2002	Chen et al	
2003/0087520	5/2003	Chen et al	
2002/0185370	12/2002	Gopalraja et al	
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6,008,117 *	12/1999	Hong et al	438/629
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6,164,128	12/2000	Santa Cruz, et al	
6,157,081	12/2000	Nariman et al	
6,157,061	12/2000	Kawata	
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MAILING ADDRESS OF SENDER (Please do not use customer number below):

Keith M. Tackett PATTERSON & SHERIDAN, L.L.P. 3040 Post Oak Blvd., Suite 1500 Houston, TX 77056-6582

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This collection of information is required by 37 CFR 1.322, 1.323, and 1.324. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 1.0 hour to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Attention Certificate of Corrections Branch, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

CERTIFICATE OF CORRECTION

PATENT NO.: 7,026,238

Page <u>2</u> of <u>3</u>

APPLICATION NO.: 10/052,681

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INVENTOR(S): Ming XI, Paul Frederick SMITH, Ling CHEN, Michael X. YANG, Mei CHANG, Fusen CHEN, Cristophe

MARCADAL, Jenny C. LIN

It is certified that error appears in the above-identified patent and that said Letters Patent are hereby corrected as shown below:

6,143,646	11/1000	Wetzel438/637
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4,962,060	10/1990	Sliwa et al 437/192
4,951,601	8/1990	Maydan et al 118/719

Item [56], References Cited, FOREIGN PATENT DOCUMENTS: Please add the following references:

JP 08-213,119

7/1996

Item [56], References Cited, OTHER PUBLICATIONS: Please add the following references:

Ghandi, Sorab K., "VLSI Fabrication Principles, Silicon and Gallium Arsenide" Second Edition, Wiley-Interscience Publication (1994), Pages 617-620 and Page 652.

R. F. Bunshah, "Handbook of Deposition Technologies for Films and Coatings", 2nd edition, Noyas Publications, NJ, USA, 1994, 261, 321-325.

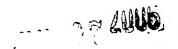
Gardner et al., "Encapsulated Copper Interconnection Device using Sidewall Barriers", Thin Solid Films 262 (1995) 104-119.

Jang et al., "Tantalum and Niobium as a Diffusion Barrier between Copper and Silicon", J. Materials Science: Materials in Electronics 7 (1996) 271-278.

Tadashi lijima, Yoshiakai Shimooka, and Kyoichi Suguro, "An Amorphous Ti-Si-N Diffusion Barrier Layer for Cu Interconnections," Vol. 78, No. 12, 1995, pages 67-74.

MAILING ADDRESS OF SENDER (Please do not use customer number below):

Keith M. Tackett PATTERSON & SHERIDAN, L.L.P. 3040 Post Oak Blvd., Suite 1500 Houston, TX 77056-6582



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CERTIFICATE OF CORRECTION

PATENT NO.: 7,026,238

Page <u>3</u> of <u>3</u>

APPLICATION NO.: 10/052,681

DATED: Apr. 11, 2006

INVENTOR(S): Ming XI, Paul Frederick SMITH, Ling CHEN, Michael X. YANG, Mei CHANG, Fusen CHEN, Cristophe

MARCADAL, Jenny C. LIN

It is certified that error appears in the above-identified patent and that said Letters Patent are hereby corrected as shown below:

Mikagi H. Ishikawa, T. Usami, M. Suzuki, K. Inoue, N. Oda, S. Chikaki, I. Sakai and T. Kikkawa. "Barrier Metal Free Copper Damascene Interconnection Technology Using Atmospheric Copper Reflow and Nitrogen Doping in SiOF Film." 1996 IEEE. Pp. 365-368.

Y. Shacham-Diamand. V. Dubin, and M. Angyal "Electroless Copper Deposition for ULSI" 1995 Elsevier Science S.A., pp. 93-103.

Electromigration and Diffusion in Pure Cu and Cu(Sn) Alloys. C. K. Hu, K. L. Lee, D. Gupta, and P. Blauner, Mat. Res. Soc. Symp. Vol 427 (96-105).

Electromigration Failure Distributions for Multi-Large Interconnects as a Function of Line Width Experiments and Simulation, D.D. Brown, J.E. Sanchez, Jr., V. Pham, P.R. Besser, M.A. Korhonen, and C.Y. Li, Mat. Res. Soc. Symp. Vol 427.

USSN Serial No.: 09/635,738, Chen, et al., "Barrier Layer Structure for Copper Metallization and Method of Forming the Structure," Filed: August 09, 2000.

In the Specification

Column 5, Lines 34 and 35: Change each instance of "MHZ" to --MHz--

Column 5, Line 35: Add a period after "MHz"

Column 7, Line 47: Change "dc" to --DC--

Column 8, Line 12: After "fill", insert --of--

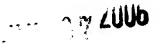
Column 8, Line 33: Change "Ta/aN" to --Ta/TaN--

MAILING ADDRESS OF SENDER (Please do not use customer number below):

Keith M. Tackett PATTERSON & SHERIDAN, L.L.P. 3040 Post Oak Blvd., Suite 1500 Houston,-TX 77056-6582

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If you need assistance in completing the form, call 1-800-PTO-9199 and select option 2.



JUN 3 0 2006 United States Patent and Trademark Office

UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandria, Virginia 22313-1450 www.uspta.gov

NOTICE OF ALLOWANDER DE

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EXAMINER

PERALTA, GINETTE

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SANTA CLARA, CA 95050

APPLIED MATERIALS, INC.

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ART UNIT

PAPER NUMBER

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DATE MAILED: 12/31/2003

CONFIRMATION NO. ATTORNEY DOCKET NO. FIRST NAMED INVENTOR FILING DATE APPLICATION NO. AMAT/1931.P1.CPI/ALUMINUM 4083 Ming Xi 01/17/2002 10/052,681

TITLE OF INVENTION: RELIABILITY BARRIER INTEGRATION FOR CU APPLICATION

APPLN. TYPE	SMALL ENTITY	ISSUE FEE	PUBLICATION FEE	TOTAL FEE(S) DUE	DATE DUE
lenoisivorquon	NO	\$1330	\$300	\$1630	03/31/2004

THE APPLICATION IDENTIFIED ABOVE HAS BEEN EXAMINED AND IS ALLOWED FOR ISSUANCE AS A PATENT. PROSECUTION ON THE MERITS IS CLOSED. THIS NOTICE OF ALLOWANCE IS NOT A GRANT OF PATENT RIGHTS. THIS APPLICATION IS SUBJECT TO WITHDRAWAL FROM ISSUE AT THE INITIATIVE OF THE OFFICE OR UPON PETITION BY THE APPLICANT. SEE 37 CFR 1.313 AND MPEP 1308.

THE ISSUE FEE AND PUBLICATION FEE (IF REQUIRED) MUST BE PAID WITHIN THREE MONTHS FROM THE MAILING DATE OF THIS NOTICE OR THIS APPLICATION SHALL BE REGARDED AS ABANDONED. STATUTORY PERIOD CANNOT BE EXTENDED. SEE 35 U.S.C. 151. THE ISSUE FEE DUE INDICATED ABOVE REFLECTS A CREDIT FOR ANY PREVIOUSLY PAID ISSUE FEE APPLIED IN THIS APPLICATION. THE PTOL-85B (OR AN EQUIVALENT) MUST BE RETURNED WITHIN THIS PERIOD EVEN IF NO FEE IS DUE OR THE APPLICATION WILL BE REGARDED AS ABANDONED.

HOW TO REPLY TO THIS NOTICE:

I. Review the SMALL ENTITY status shown above.

If the SMALL ENTITY is shown as YBS, verify your current SMALL ENTITY status:

A. If the status is the same, pay the TOTAL FEE(S) DUE shown

B. If the status is changed, pay the PUBLICATION FEE (if required) and twice the amount of the ISSUE FEE shown above and notify the United States Patent and Trademark Office of the change in status, or

If the SMALL ENTITY is shown as NO:

A. Pay TOTAL FEE(S) DUE shown above, or

B. If applicant claimed SMALL ENTITY status before, or is now claiming SMALL ENTITY status, check the box below and enclose the PUBLICATION FEE and 1/2 the ISSUE FEE shown above.

 Applicant claims SMALL ENTITY status. See 37 CFR 1.27.

II. PART B - FEE(S) TRANSMITTAL should be completed and returned to the United States Patent and Trademark Office (USPTO) with your ISSUE FRE and PUBLICATION FEE (if required). Even if the fee(s) have already been paid, Part B - Fee(s) Transmittal should be completed and returned. If you are charging the fec(s) to your deposit account, section "4b" of Part B - Fee(s) Transmittal should be completed and an extra copy of the form should be submitted.

III. All communications regarding this application must give the application number. Please direct all communications prior to issuance to Mail Stop ISSUE FEE unless advised to the contrary.

IMPORTANT REMINDER: Utility patents issuing on applications filed on or after Dec. 12, 1980 may require payment of maintenance fees. It is patentec's responsibility to ensure timely payment of maintenance fees when due.

Attachment(s)

1⊠ Notice of References Cited (PTO-892)

4 Examiner's Comment Regarding Requirement for Deposit

						<u></u>	Sheet 1 of 1 s	heets
		601	P.E. Todoma	ork Office	Docket No).	Serial No.	
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Examiner nitial		Document Number	Issue Date	Applicant(s) Name	Class		Appropriate	
SP	A1	6;607,977	08/19/2003	Rozbicki, et al.	438	627	09/26/2001	
MP	A2	6,498,091	12/24/2002	Chen, et al.	438	627	11/01/2000	
11 0	АЗ	2003/0087520	05/08/2003	Chen, et al.	438	643	11/07/2002	
UP P	A4	2002/0185370	12/12/2002	Gopalraja, et al.	204	192.17	07/16/2002	
GP GP	A5	2002/0029958	03/14/2002	Chiang, et al.	204	192.1	06/20/2001	
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U.S. Patent *Examiner	. Docum	Document	Issue	Applicant(s)	Class	Subclass	Filing Date If	
Initial	_	Number	Date	Name			Appropriate	
SP	A1	6,297,114	10/02/2001	Iwata, et al.	438	305	12/04/1998	
MP	A2	5,792,272	08/11/1998	Van Os, et al.	11B	723 IR	08/12/1997	
NP	АЗ	5,759,635	06/02/1998	Logan	427	490	07/03/1996	
MD	A4	5,565,074	10/15/1996	Qian, et al.	204	298.08	07/27/1995	
PIP	A5	5,397,962	03/14/1995	Moslehi	315	111.51	06/29/1992	*
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Notice of References Cited	Examiner Ginette Peralta	Art Unit 2814	Page 1 of 1	

U.S. PATENT DOCUMENTS

	_	:		U.S. PATENT DOCUMENTS	
*	• [Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification 438/629
\dashv	A.	US-6,008,117	12-1999	Hong et al.	
	В	US-6,093,639	07-2000	Wu et al.	438/629
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NON-PATENT DOCUMENTS

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"A copy of this reference is not being furnished with this Office action, (See MPEP § 707.05(6).)
Dates in MM-YYYY formal are publication dates, Classifications may be US or foreign.





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UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address: COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandria, Virginia 22313-1450 www.uspto.gov

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/052,681	01/17/2002	Ming Xi	AMAT/1931.P1.CPI/ALUMINI	UM 4083
32588	7590 06/19/2003			
	ATERIALS, INC.		EXAM	INER
	BLVD. M/S 2061 RA, CA 95050	-	PERALTA,	GINETTE
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Please find below and/or attached an Office communication concerning this application or proceeding.



	• • • • • • • • • • • • • • • • • • • •	Application No.	Applicant(s)
	Office Action Commons	10/052,681	XI ET AL.
(Office Action Summary	Examiner	Art Unit
		Ginette Peralta	2814
Th Period for Re	e MAILING DATE of this communication app ply	ears on the cover sheet with the c	orrespondence address
THE MAIL - Extensions after SIX (6) - If the period - If NO period - Failure to re - Any reply re	ENED STATUTORY PERIOD FOR REPLY ING DATE OF THIS COMMUNICATION. of time may be available under the provisions of 37 CFR 1.13 MONTHS from the mailing date of this communication. If for reply specified above is less than thirty (30) days, a reply of for reply is specified above, the maximum statutory period we eply within the set or extended period for reply will, by statute, seeived by the Office later than three months after the mailing and term adjustment. See 37 CFR 1.704(b).	36(a). In no event, however, may a reply be time within the statutory minimum of thirty (30) days will apply and will expire SIX (6) MONTHS from cause the application to become ABANDONE	nely filed s will be considered timely. the mailing date of this communication. C (35 U.S.C. § 133).
1)⊠ Re	sponsive to communication(s) filed on 31 N	<u> 1arch 2003</u> .	
2a)∐ Thi	s action is FINAL . 2b) Thi	s action is non-final.	
	ace this application is in condition for allowants sed in accordance with the practice under the following the conditions of Claims		
4)⊠ Clai	m(s) 1-38 is/are pending in the application		
4a) (Of the above claim(s) is/are withdray	vn from consideration.	
5)☐ Clai	m(s) is/are allowed.		
6)⊠ Clai	m(s) <u>1-38</u> is/are rejected.		(O) (D)
7) Clair	m(s) is/are objected to.		
8)☐ Clai	m(s) are subject to restriction and/or	election requirement.	Q
Application P	apers		
9)□ The s	specification is objected to by the Examiner		
10)☐ The c	drawing(s) filed on is/are: a) accep	ted or b) objected to by the Exar	niner.
Apı	plicant may not request that any objection to the	drawing(s) be held in abeyance. Se	ee 37 CFR 1.85(a).
11)☐ The r	proposed drawing correction filed on	is: a) ☐ approved b) ☐ disappro	ved by the Examiner.
If a	pproved, ∞rrected drawings are required in rep	ly to this Office action.	
12)☐ The c	oath or declaration is objected to by the Exa	aminer.	
Priority under	r 35 U.S.C. §§ 119 and 120		
13)☐ Ackr	nowledgment is made of a claim for foreign	priority under 35 U.S.C. § 119(a))-(d) or (f).
a)⊡ All	b)☐ Some * c)☐ None of:		·
1.	Certified copies of the priority documents	have been received.	
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Examiner

Ginette Peralta

Applicant(s)/Patent Under Reexamination XI ET AL.

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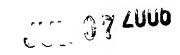
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COMBINED DECLARATION AND POWER OF ATTORNEY

As a below named inventor, I hereby declare that:

This declara	tion is of the following type:
[] [] [X]	original divisional continuation continuation-in-part
	INVENTORSHIP IDENTIFICATION
inventor (if plu	, post office address and citizenship are as stated below next to my name. I believe I and first and sole inventor (if only one name is listed below) or an original, first and join ural names are listed below) of the subject matter which is claimed and for which a paten the invention entitled:
	RELIABILITY BARRIER INTEGRATION FOR CU APPLICATION
	SPECIFICATION IDENTIFICATION
The specificat	ion of which:
[X] [] []	is attached hereto was filed on , under Serial No. , executed on even date herewith; or Express Mail No.(as Serial No. not yet known) and was amended on (if applicable) was described and claimed in PCT International Application No filed on and as amended under PCT Article 19 on
	ACKNOWLEDGMENT OF REVIEW OF PAPERS AND DUTY OF CANDOR
I hereby state including the cla	that I have reviewed and understand the contents of the above-identified specification, aims, as amended by any amendment referred to above.
I acknowledge with	the duty to disclose all information I know to be material to patentability in accordance
application, nat	of Federal Regulations, 1.56, and which is material to the examination of this nely, information where there is a substantial likelihood that a reasonable Examiner it important in deciding whether to allow the application to issue as a patent, and
[]	In compliance with this duty there is attached an Information Disclosure Statement in accordance with 37 CFR 1.98.

PRIORITY CLAIM (35 U.S.C. 119)

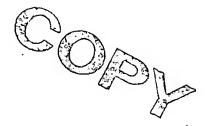
I hereby claim foreign priority benefits under Title 35, United States Code, 119, of any provisional or foreign application(s) for patent or inventor's certificate or of any PCT international application(s) designating at least one country other than the United States of America listed below, and have also identified below any provisional or foreign application(s) for patent or inventor's certificate or any PCT international application(s) designating at least one country other than the United States of America filed by me on the same subject matter having a filing date before that of the application(s) of which priority is claimed.

	[X]	No such	applications	s have bee	n filed.			•	
	[]	Such ap	plications ha	ave been fi	led as t	follows:			
A.	Prior foreign/PCT application(s) filed within 12 mos. (6 mos. for design) prior to this application, and any priority claims under 35 U.S.C. 119								
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POWER OF ATTORNEY

I hereby appoint the following attorneys and/or agents to prosecute this application and transact all business in the Patent and Trademark Office connected therewith:

> Donald Verplancken Registration No. 33,217 Michael B. Einschlag Registration No. 29,301 Peter J. Sgarbossa Registration No. 25,610 Lawrence Edelman Registration No. 25,226 Michael L. Sherrard Registration No. 28,041 Raymond Kam-On Kwong Registration No. 37,165 James C. Wilson Registration No. 35,412 Robert W. Mulcahy Registration No. 25,436 Walter Benjamin Glenn Registration No. 44,713 B. Todd Patterson Registration No. 37,906 Raymond R. Moser, Jr. Registration No. 34,682 Keith M. Tackett Registration No. 32,008 Douglas H. Elliott Registration No. 32,982 William B. Patterson Registration No. 34,102



Send correspondence to:

Direct telephone calls to:

Patent Counsel Applied Materials, Inc. P.O. Box 450-A

Santa Clara, CA 95052

B. Todd Patterson

MOSER, PATTERSON & SHERIDAN, L.L.P.

713-623-4844

DECLARATION

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and, further, that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Sec. 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patents issued thereon.

Full name of first inver	ntor: MING XI		
Inventor's signature:		Date:	
Residence:	138 Beaumere Way Milpitas, CA 95035		
Post Office Address:	SAME AS ABOVE		
	U.S.A.	Country of Citizenship:	P.R. CHINA
Full name of second in Inventor's signature:	nventor: PAUL FREDERICK S	MITH Date: 01/10	102
Residence:	225 E. Taylor Street #4		
Dook Office A Literature	San Jose, CA 95112		
Post Office Address:	SAME AS ABOVE U.S.A	Country of Citizenship:	USA
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	955 Stonehust Way Campbell, CA, 9500	98	